

RD Number: RD128

RD Title: TB67H401FTG Evaluation circuit

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	CVM1	1	100uF	KMG50VB100M	NIPPON CHEMI-CON	Electrolytic capacitor		
2	CVM2	1	0.1uF	GRM319R72A104KA01D		Ceramic capacitor		
3	R_RSA	1	0.22Ω	ERJ-12ZQJR22U		Chip resistor		
4	R_RSB	1	0.22Ω	ERJ-12ZQJR22U		Chip resistor		
5	R_OUTA	0	0.22Ω	ERJ-12ZQJR22U		Chip resistor		✓
6	R_OUTB	0	0.22Ω	ERJ-12ZQJR22U		Chip resistor		✓
7	R_VRFA1	0				Leaded resistor		✓
8		2	-	PD-10	Mac8	Socket pin		
9	R_VRFA2	0				Leaded resistor		✓
10		2	-	PD-10	Mac8	Socket pin		
11	R_VRFB1	0				Leaded resistor		✓
12		2	-	PD-10	Mac8	Socket pin		
13	R_VRFB2	0				Leaded resistor		✓
14		2	-	PD-10	Mac8	Socket pin		
15	R_LO	1	10kΩ	MFS1/4CC1002F		Leaded resistor		
16		2	-	PD-10	Mac8	Socket pin		
17	R_FBA	1	10kΩ	MFS1/4CC1002F		Leaded resistor		
18		2	-	PD-10	Mac8	Socket pin		
19	R_FBB	1	10kΩ	MFS1/4CC1002F		Leaded resistor		
20		2	-	PD-10	Mac8	Socket pin		
21	R_OSCM	0	5.1kΩ	MFS1/4CC5101F		Leaded resistor		✓
22		0	-	PD-10	Mac8	Socket pin		✓
23		1	5.1kΩ	RK73B2BTDD512J		Chip resistor		
24	C_OSCM	0	270pF			Ceramic capacitor		✓
25		1	270pF	GRM31A7U3A271JW31D		Ceramic capacitor		
26	C_VCC	1	0.1uF	GRM319R72A104KA01D		Ceramic capacitor		

27	C_VREFA	1	0.1uF	GRM319R72A104KA01D		Ceramic capacitor		
28	C_VREFB	1	0.1uF	GRM319R72A104KA01D		Ceramic capacitor		
29	C_VDD	1	10uF	KMG50VB10M	NIPPON CHEMI-CON	Electrolytic capacitor		
30	C_OUTA+	0						✓
31	C_OUTA-	0						✓
32	C_OUTB-	0						✓
33	C_OUTB+	0						✓
34	VDD	1	-	ST-1-3	Mac8	Check pin		
35	GND	8	-	ST-1-3	Mac8	Check pin		
36	INB1	1	-	ST-1-3	Mac8	Check pin		
37	INB2	1	-	ST-1-3	Mac8	Check pin		
38	TBLANKAB	1	-	ST-1-3	Mac8	Check pin		
39	OUTA+	1	-	ST-1-3	Mac8	Check pin		
40	OUTA-	1	-	ST-1-3	Mac8	Check pin		
41	OUTB-	1	-	ST-1-3	Mac8	Check pin		
42	OUTB+	1	-	ST-1-3	Mac8	Check pin		
43	RSA	1	-	ST-1-3	Mac8	Check pin		
44	RSB	1	-	ST-1-3	Mac8	Check pin		
45	VM	1	-	ST-1-3	Mac8	Check pin		
46	VCC	1	-	ST-1-3	Mac8	Check pin		
47	LO	1	-	ST-1-3	Mac8	Check pin		
48	FBB	1	-	ST-1-3	Mac8	Check pin		
49	FBA	1	-	ST-1-3	Mac8	Check pin		
50	HBMODE	1	-	ST-1-3	Mac8	Check pin		
51	VREFB	1	-	ST-1-3	Mac8	Check pin		
52	VREFA	1	-	ST-1-3	Mac8	Check pin		
53	OSCM	1	-	ST-1-3	Mac8	Check pin		
54	INA1	1	-	ST-1-3	Mac8	Check pin		
55	INA2	1	-	ST-1-3	Mac8	Check pin		
56	PWMA	1	-	ST-1-3	Mac8	Check pin		
57	PWMB	1	-	ST-1-3	Mac8	Check pin		
58	INB1	1	-	2130S1*3GSE	Linkman	Jumper		
59		1	-	2180BBA	Linkman	Short pin		
60	INB2	1	-	2130S1*3GSE	Linkman	Jumper		

61		1		2180BBA	Linkman	Short pin		
62	TBLANKAB	1	-	2130S1*3GSE	Linkman	Jumper		
63		1		2180BBA	Linkman	Short pin		
64	HBMODE	1	-	2130S1*3GSE	Linkman	Jumper		
65		1		2180BBA	Linkman	Short pin		
66	INA1	1	-	2130S1*3GSE	Linkman	Jumper		
67		1		2180BBA	Linkman	Short pin		
68	INA2	1	-	2130S1*3GSE	Linkman	Jumper		
69		1		2180BBA	Linkman	Short pin		
70	PWMA	1	-	2130S1*3GSE	Linkman	Jumper		
71		1		2180BBA	Linkman	Short pin		
72	PWMB	1	-	2130S1*3GSE	Linkman	Jumper		
73		1		2180BBA	Linkman	Short pin		
74	JP_VDD	1	-	2130S1*2GSE	Linkman	Jumper		
75		1		2180BAA	Linkman	Short pin		
76	JP_FBB	1	-	2130S1*2GSE	Linkman	Jumper		
77		1		2180BAA	Linkman	Short pin		
78	CN1	1	-	DF1BZ-2P-2.5DSA	Hirose Electric	Connector		
79	CN2	1	-	DF1BZ-2P-2.5DSA	Hirose Electric	Connector		
80	CN3	1	-	DF1BZ-2P-2.5DSA	Hirose Electric	Connector		
81	IC	1	-	TB67H401FTG		IC		
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